

Title (en)  
ELECTRONIC ASSEMBLY

Title (de)  
ELEKTRONISCHE BAUEINHEIT

Title (fr)  
MODULE ÉLECTRONIQUE

Publication  
**EP 3625587 A1 20200325 (DE)**

Application  
**EP 18714488 A 20180328**

Priority  
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Abstract (en)  
[origin: WO2018210474A1] The invention relates to an electronic assembly (10), particularly a sensor device, having a housing (12) sealed against the ingress of media, having electronic components (31, 32) arranged in an interior space (14; 14a) of the housing (12) and having a filling element (35; 35a), which extends at least almost as far as the electronic components (31, 32) or is in contact therewith.

IPC 8 full level  
**G01S 15/931** (2020.01)

CPC (source: EP)  
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Citation (search report)  
See references of WO 2018210474A1

Designated contracting state (EPC)  
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DOCDB simple family (publication)  
**WO 2018210474 A1 20181122**; CN 110678779 A 20200110; DE 102017208352 A1 20181122; EP 3625587 A1 20200325

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**EP 2018057867 W 20180328**; CN 201880032726 A 20180328; DE 102017208352 A 20170518; EP 18714488 A 20180328